

VAPOR DEPOSITION MATERIAL AND METHOD FOR MANUFACTURING SAME

ABSTRACT

Provided is an evaporation material wherein the evaporation material comprises one or more types among Au, Ag, Pt, Pd and their alloys, micropores are formed on a surface of the evaporation material, and a number of the micropores having an equivalent circle diameter of 0.1 μm or more and 10.0 μm or less is one or more micropores per 500 μm^2 . Additionally provided is an evaporation material wherein a hydrogen content in the evaporation material is 10 wtppm or less. An object of the present invention is to provide an evaporation material for use in a vacuum deposition method capable of suppressing the bumping phenomenon upon melting the evaporation material.

Fig. 3